

In the Specification

Kindly replace paragraph [0085] with the following:

[0085] Figs. 5 to 7 show RTM molding method and device according to another embodiment different from the above-described first embodiment. In Fig. 5, an intermediate member 24 consisting of a perforated plate and a perforated film (in this embodiment, a perforated plate) is set between an upper die 21 and a lower die 22 of a mold 20. Grooves 36a, 36b (Fig. 6) for resin paths are processed on upper die 21 so as to extend over the entire area. A clearance 25, a fine clearance 25 of ~~about 0.5 to~~ about 1 mm in this embodiment, is formed between perforated plate 24 and upper die 21. Further, a more efficient resin flow and impregnation becomes possible if the positions of holes of a perforated plate or a perforated film coincide with the positions of the grooves formed on the upper die. Most of the resin flown from a resin injection member 26 sealed with a seal member 28 (for example, a rubber block) flows to the above-described clearance 25, and is filled in the space of the clearance 25. On perforated plate 24, fine through holes 24a (diameter: about 0.5 to about 3.5 mm) are opened over the entire area at a pitch of 3 to 8 mm. Therefore, the flow resistance of the resin of the perforated plate 24 is much higher than that in the resin flow to the above-described clearance 25. A reinforcing fiber substrate 23 is set in a cavity 31, upper die 21 is clamped, and vacuum suction is carried out through a discharge member 27 sealed with a seal member 29. The resin having been charged in the above-described clearance 25 is pressurized, and the resin is injected at a pressurized condition at a time over the entire area from through holes 24a of perforated plate 24. An excessive resin after impregnation flows a film gate/runner provided on the circumference of cavity 31, and it is discharged from discharge tube 27 to outside. After impregnation over the entire area, the discharge tube 27 is closed, and while the resin pressure is maintained, heating/curing is carried out. In die opening, upper die 21 is lifted up, a molded product is taken out together with perforated plate 24 from lower die 22, and the molded product is separated from the perforated plate 24. In a case where the separation from perforated plate 24 or a post processing for a molded product adhered with resin projections is troublesome, it had better to dispose a cloth for release (a woven fabric made of polypropylene or

polyethylene: also called a peel ply) between perforated plate 24 and reinforcing fiber substrate 23 beforehand. Further, as the case may be, only a cloth for release may be disposed without disposing perforated plate 24.